

Serial No.: 09/396,352

10/13/2000

DOCKET NO.: NOVA-002-USAP

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of: Tümay TÜRER

Serial No.: 09/396,352

Art Unit: 2736

Filed: September 14, 1999

Examiner: HUANG, S

For: TAG HAVING A SEMICONDUCTOR CHIP AND METHOD OF ATTACHMENT  
ARTICLETRANSMITTAL

Assistant Commissioner of  
Patents and Trademarks  
Washington, D.C. 20231  
Box: Non-Fee Amendments

Sir: TRANSMITTED HERewith IS

☐ A RESPONSE, ☒ AN AMENDMENT, ☐ AN AMENDMENT AFTER FINAL,

IN THE ABOVE-IDENTIFIED APPLICATION.

☐ Small entity status of this application under 37 CFR §1.9(f) is established  
by a verified statement under 37 CFR §1.27

☐ previously submitted.  
☐ submitted herewith.

☒ No additional fee is required, as shown below.

CLAIMS PENDING AFTER AMENDMENT		CLAIMS PREVIOUSLY PAID		NEW CLAIMS EXTRA		ADDITIONAL FEES			
						SMALL ENTITY		OTHER THAN SMALL ENTITY	
TOTAL	24	MINUS	25	=	0	x\$9=	0.00	x\$18=	0.00
INDEP	2	MINUS	3	=	0	x40=	0.00	x\$80=	0.00
NEW MULTIPLE DEPENDENT CLAIMS					0	x\$135=	0.00	x\$270=	0.00
AND CLAIMS DEPENDENT THEREON					0	x\$135=	0.00	x\$270=	0.00
TOTAL ADDITIONAL FEE						0.00		0.00	

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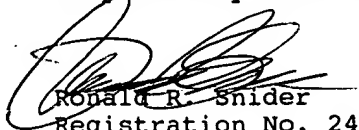
10/13/2000

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☒

This amount is believed to be correct, however, the Commissioner is hereby authorized to charge any deficiency or credit any overpayment to Deposit Account No. 19-2816. This authorization applies to both filing fees under 37 CFR §1.16 and processing fees (such as extension of time) under 37 CFR §1.17. A duplicate copy of this transmittal is attached.

Respectfully Submitted,



Ronald R. Snider

Registration No. 24,962

Date: October 13, 2000

Snider & Associates

Ronald R. Snider

P.O. Box 27613

Washington, D.C. 20038-7613

(202) 347-2600

RRS/bam

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ARTICLE

AMENDMENT

Assistant Commissioner of  
Patents and Trademarks  
Washington, D.C. 20231  
Box: Non-Fee Amendments

Sir:

This Amendment is responsive to the Office Action dated July 19, 2000. Claims 1 and 3 - 26 are pending in this application and have been rejected.

Please amend this application as follows:

IN THE SPECIFICATION:

Please amend the specification as follows:

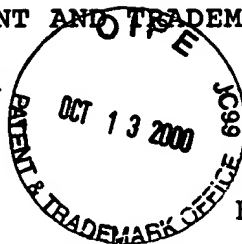
Page 4, line 11, delete "The prototype chip designed and fabricated contains connections pads for testing. The final chip ready for manufacture will not contain any connections pads and its size will be significantly reduced to  $\leq 9 \text{ mm}^2$ ."

Page 7, line 10, delete "for this test version"

Page 7, line 18, delete "Eventually, the ID codes will" and substitute therefore ---The ID codes can---

Page 8, line 4, delete "cf." and substitute therefore ---see--

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